
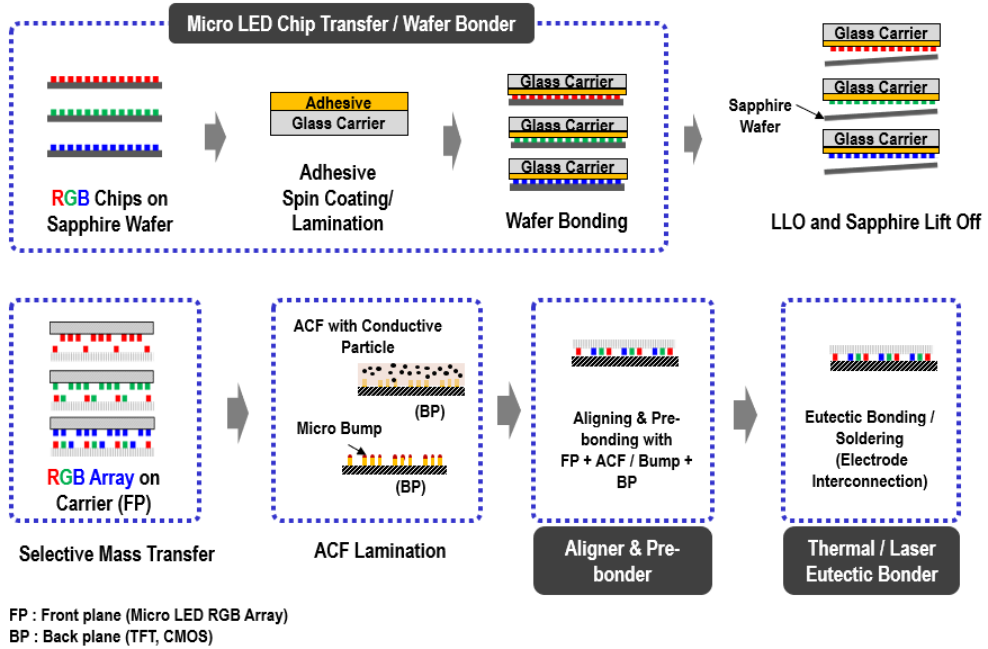


# iMiD 2022

The 22nd International Meeting on Information Display  
August 23-26, 2022 / BEXCO, BUSAN, KOREA



<b>Company Name</b>	KOSTEK Systems, Inc.	<b>Company Logo</b>
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<b>Exhibitor Introduction</b>	<p>KOSTEK Systems has been conducting business in the Semiconductor Equipment and Micro LED Display Transfer Equipment since its establishment in 2000. <b>Main Products are Micro LED Display Transfer System, Wafer Bonding System and Wafer Transfer System.</b> (1) <b><u>Micro LED (Display) Transfer Equipment includes Chip Transfer System(Wafer Bonder), Aligner &amp; Pre-bonder and Post Bonder(Thermal Eutectic Bonder / Laser Eutectic Bonder).</u></b> (2) Wafer Bonding System includes Temporary Wafer Bonder &amp; De-bonder, Permanent Wafer to Wafer bonder and Collective die to wafer bonder. (3) Wafer Transfer System includes Vacuum Cluster System, EFEM and Robot.</p> <p>We have been selling our products to Samsung Electronics, SK hynix, LC Square, Seoul Viosys, Nepes, Wonik IPS, Eugene Tech, SGS and Ulvac Korea etc.</p>	
<b>Exhibit Description</b>	<p><b>Micro LED (Display) Transfer Equipment</b> <b>These systems are used for manufacturing Micro LED TV, Smartwatch, AR/VR Display etc.</b></p> <p><b>(1) Micro LED chip transfer system (Wafer Bonder)</b> This System transfers all the Micro LED Chips from sapphire substrate to another glass carrier by wafer bonding method and laser lift off.</p>	



## (2) Aligner & Pre-bonder

This System aligns, presses softly and pre-bonds between micro LED RGB array on glass carrier and TFT substrate which is laminated with ACF in Atm or Vacuum.

## (3) Thermal / Laser Eutectic bonder

This System presses and bonds finally by heater chuck or laser after pre-bonding between micro LED RGB array and TFT substrate in vacuum.

## (Micro LED Display Transfer Equipment)



<Chip transfer system(Wafer Bonder)>

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**<Aligner & Pre-bonder>**



**<Thermal / Laser eutectic bonder>**